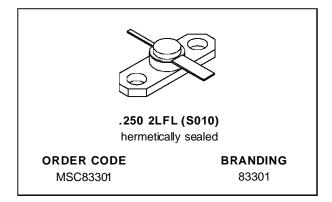
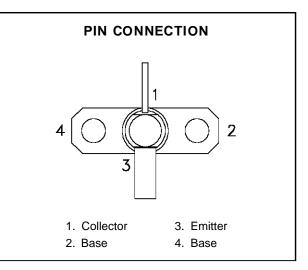


MSC83301

RF & MICROWAVE TRANSISTORS GENERAL PURPOSE AMPLIFIER APPLICATIONS

- REFRACTORY/GOLD METALLIZATION
- EMITTER SITE BALLASTED
- VSWR CAPABILITY ∞:1 @ RATED CONDITIONS
- HERMETIC STRIPAC[®] PACKAGE
- $P_{OUT} = 1.0$ W MIN. WITH 7.0 dB GAIN @ 3.0 GHz





DESCRIPTION

The MSC83301 is a common base hermetically sealed silicon NPN microwave power transistor utilizing an overlay, emitter site ballasted geometry with a refractory gold metallization system. This device is capable of withstanding an infinite load VSWR at any phase angle under rated conditions. The MSC83301 is designed for Class C amplifier/oscillator applications in the 1.0 - 3.0 GHz frequency range.

ABSOLUTE MAXIMUM RATINGS ($T_{case} = 25^{\circ}C$)

Symbol	Parameter	Value	Unit	
PDISS	Power Dissipation [*] $(T_C \le 50^{\circ}C)$	6.0	W	
Ι _C	Device Current* 200		mA	
V _{CC}	Collector-Supply Voltage*	30	V	
TJ	Junction Temperature	200	°C	
T _{STG}	Storage Temperature	– 65 to +200	°C	

THERMAL DATA

RTH(j-c)	Junction-Case Thermal Resistance*	25	°C/W		
*Applies only to rated RF amplifier operation					

MSC83301

ELECTRICAL SPECIFICATIONS $(T_{case} = 25^{\circ}C)$

STATIC

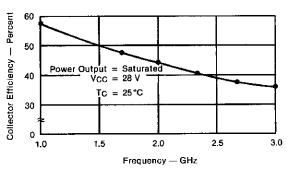
Symbol	Test Conditions	Value			11:0:4		
		Min.	Тур.	Max.	Unit		
BV _{CBO}	$I_C = 1 \text{ mA}$	$I_E = 0 mA$		45	_		V
BVEBO	$I_E = 1 \text{ mA}$	$I_C = 0 \text{ mA}$		3.5	—	_	V
BVCER	I _C = 5 mA	$R_{BE} = 10 \ \Omega$		45	_	_	V
Ісво	$V_{CB} = 28V$			_	_	0.5	mA
h _{FE}	$V_{CE} = 5 V$	$I_C = 100 \text{ mA}$		30		300	

DYNAMIC

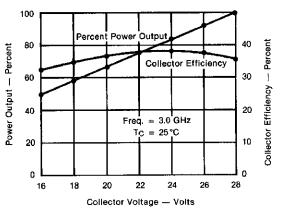
Cymhal	Test Conditions		Value				
Symbol	Test Conditions			Min.	Тур.	Max.	Unit
Роит	f = 3.0 GHz	$P_{IN} = 0.20 \text{ W}$	$V_{CC} = 28 V$	1.0	1.3		W
ης	f = 3.0 GHz	$P_{IN}=0.20\ W$	$V_{CC} = 28 V$	33	36	—	%
PG	f = 3.0 GHz	$P_{IN}=0.20\ W$	$V_{CC}=28\ V$	7.0	8.1	—	dB
Сов	f = 1 MHz	$V_{CB} = 28 V$		—		3.5	pF

TYPICAL PERFORMANCE

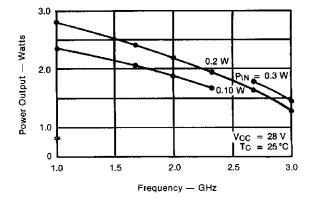




PERCENT POWER OUTPUT & COLLECTOR EFFICIENCY vs COLLECTOR VOLTAGE

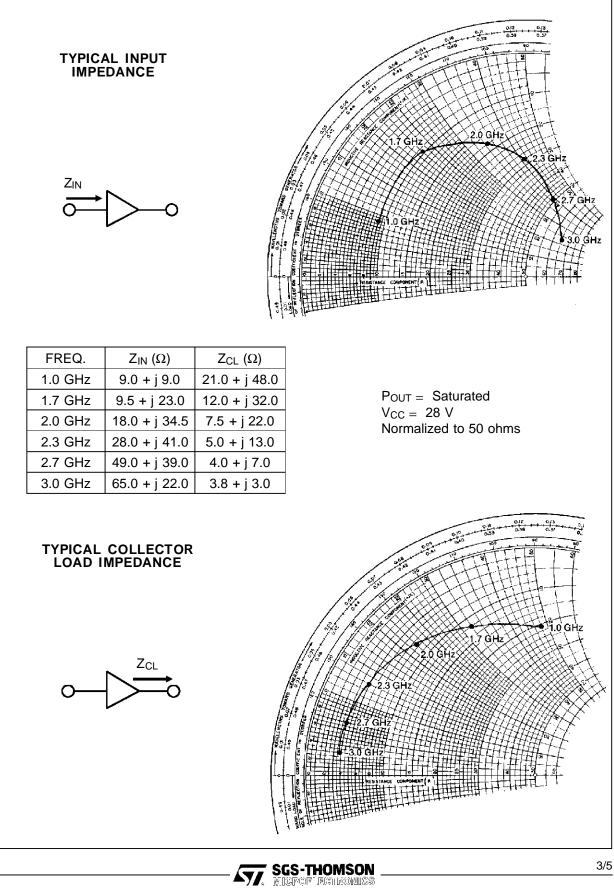


TYPICAL POWER OUTPUT vs FREQUENCY



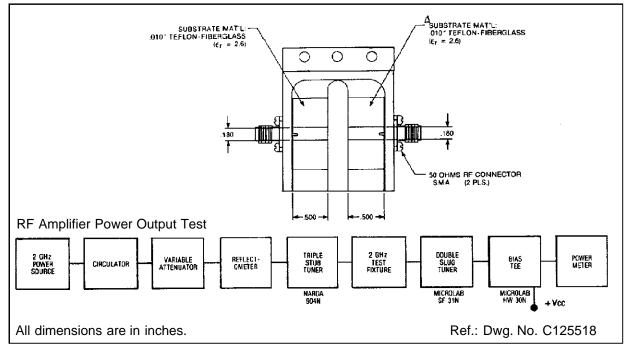


IMPEDANCE DATA



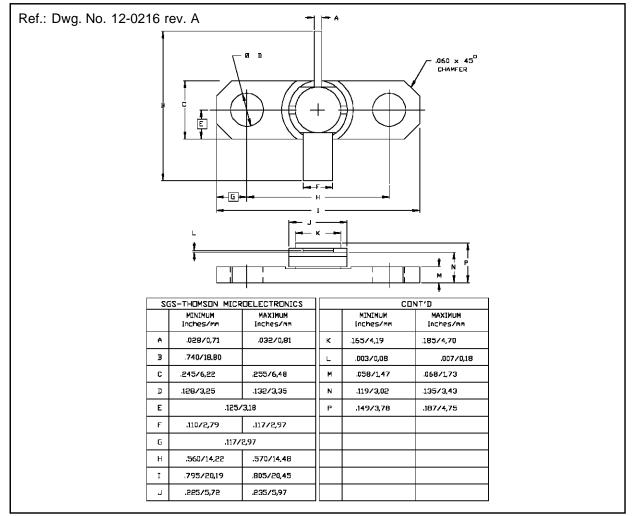
MSC83301

TEST CIRCUIT





PACKAGE MECHANICAL DATA



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